

IN THE CLAIMS:

Please CANCEL claims 3, 5, 7 and 9-23 without prejudice to or disclaimer of the recited subject matter.

Please AMEND claims 1, 6 and 8 as follows. For the Examiner's convenience, all claims currently pending in this application have been reproduced below:

1. (Currently Amended) A scanning exposure apparatus for exposing a substrate to a pattern of an original through a projection optical system, while scanning the original and the substrate, comprising:

a first detection system which detects a first substrate reference mark corresponding to the substrate through said projection optical system from at least one of an on-axis position on an optical axis of said projection optical system and an off-axis position apart from the optical axis in a scanning direction; and

an alignment system which aligns the original and the substrate based on a detection result of said first detection system,

wherein said first detection system detects a positional error between a measurement mark which is formed on the original, and the first substrate reference mark, and

wherein said alignment system calculates a deformation amount of the original based on the detection result of said first detection system.

2. (Original) An apparatus according to claim 1, wherein the first substrate reference mark is formed on a stage which moves the substrate.

3. (Canceled)

4. (Original) An apparatus according to claim 1, further comprising a second detection system which detects a second substrate reference mark corresponding to the substrate through said projection optical system from an off-axis position apart from the optical axis in a direction perpendicular to the scanning direction.

5. (Canceled)

6. (Currently Amended) An apparatus according to claim 1, further comprising a ~~third~~ second detection system which detects a ~~third~~ second substrate reference mark corresponding to the substrate not through said projection optical system.

7. (Canceled)

8. (Currently Amended) An apparatus according to claim 1, further comprising a ~~fourth~~ second detection system which detects a ~~fourth~~ second substrate reference mark corresponding to the substrate through said projection optical system.

9-23. (Canceled)

24. (Original) A device manufacturing method, comprising a step of exposing a substrate to a pattern using a scanning exposure apparatus defined in claim 1.